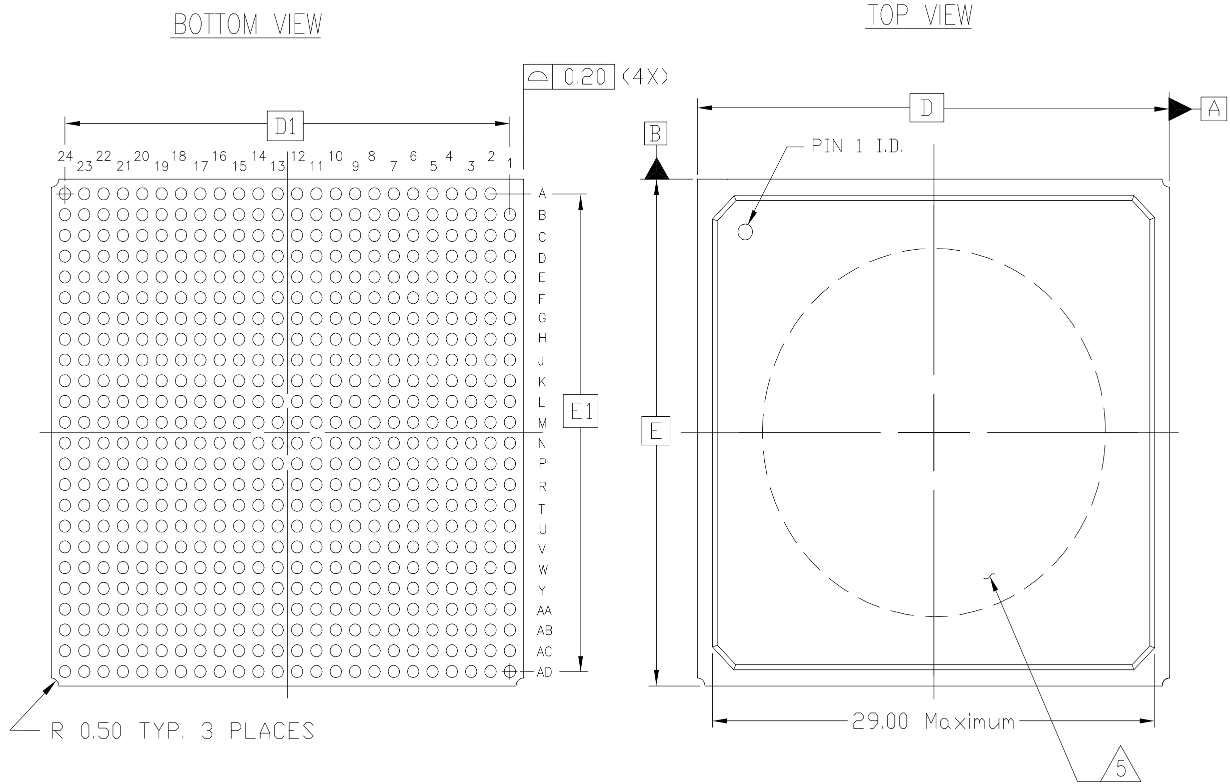
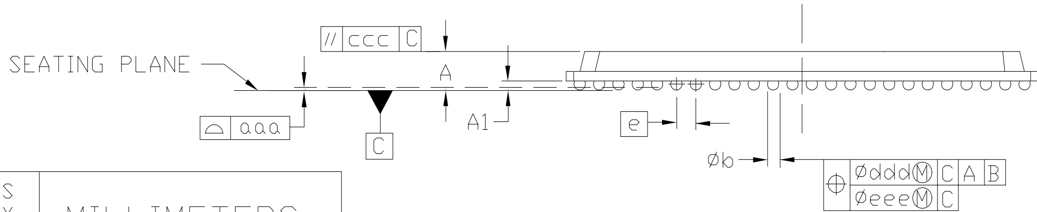
Molded BGA (BG575/BGG575) Package





SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	—	2.33	2.60
A_1	0.50	0.60	0.70
D/E	31.00 BSC		
D_1/E_1	29.21 REF		
e	1.27BSC		
Øb	0.60	0.75	0.90
aaa	—	—	0.20
ccc	—	—	0.35
ddd	—	—	0.30
eee	—	—	0.15
M	24		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-BAN-1 (DEPOPULATED)
4. NO SOLDER BALL AND LAND ON A1.
5. (5) HEAT SINK OPTION

575-BALL MOLDED BGA, 1.27MM PITCH (BG575/BGG575)

© 2004, 2005 Xilinx, Inc. All rights reserved. All Xilinx trademarks, registered trademarks, patents, and disclaimers are as listed at http://www.xilinx.com/legal.htm.
All other trademarks and registered trademarks are the property of their respective owners. All specifications are subject to change without notice.